

JG15S UV Laser Cutting Machine



USAGE

This machine is equipped with Imported UV laser system, granite base, high precision linear motor, small size table, it can high efficiently cut FPC, RF, thin multi-layer board, cover layer, and open window, remove cover. as well as cutting variety of substrates, such as ceramic, silicon etc.

ADVANTAGE

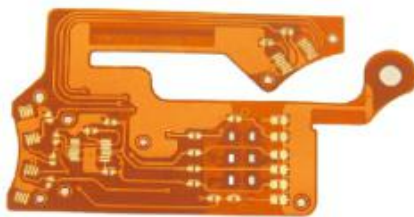
- (1) Security and Reliability: High security and reliability of marble base as well as fully enclosed design.
- (2) High Precision: Equipped with imported Linear motor system and super high precision scan galvanometer, high cutting precision, great stability.
- (3) Long lifetime: Equipped with all imported solid UV laser system, great beam quality, stable pulse energy, long lifetime.
- (4) Great cutting quality: Cold laser cutting process, without burrs around edge, small carbonization
- (5) Automatics: Automatically focus, automatically align, automatically positioning , automatically compensation, automatic expansion compensation and unique cutting preview intelligent design.
- (6) Multi-panel cutting: Array several panels on the table in one time to cut, improve cutting efficiency.

APPLICATIONS

Cutting Cover layer, FPC, Rigid-Flexible board and thin multi-layer board, and opening window and opening cover.



Cover layer



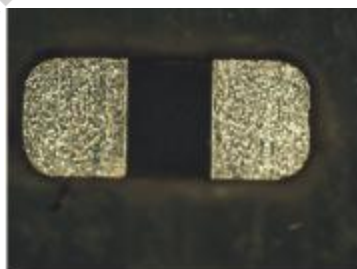
FPC, RF board



Aluminum



Ceramics



Tin alloys



Silicon

TECHNICAL PARAMETER

Specifications of UV Laser Cutting Machine	
Model	JG15S
Wavelength	355nm
Laser Power	Option (Standard 10W)
Laser Frequency	30-120kHz
Maximum Processing Size	250mm×300mm
Maximum Operating Speed	500mm/s
Positioning Accuracy of Table	±3μm
Repetitive Positioning Accuracy of Table	±1μm
Total Accuracy	±20um
light spots	20±5μm
Scanning range	40 mm x 40mm
File Format	*.gbr & *.dxf & *.lay
Electric Power Supply	AC220V/1.5kW; AC380V/1.5kW
Dimensions(L x W x H)	1050mm×1000mm×1610mm
Weight	700kg
Environmental Temperature	20±2℃
Environmental Humidity	Non-condensing
Ground Amplitude	≤5μm
Ground Pressure	≥700Kgf/m ²

